

Silicon NPN SMD triode;

1: base 2: emitter 3: collector

encapsulation mode: SOT-23

Ouline example

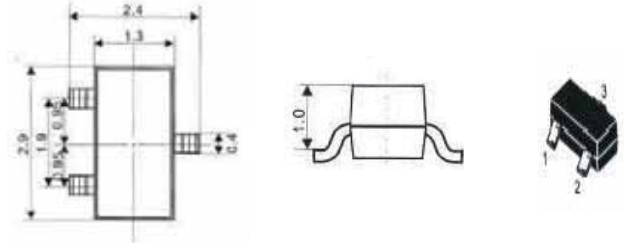
P/N suffix V means AEC-Q101 qualified, e.g:BC817V

P/N suffix V means Halogen-free

Marking code: BC817

Classification of hFE

Rank	BC817-16	BC817-25	BC817-40
Range	100-250	160-400	250-600
Marking	6A	6B	6C



Maximum ratings(Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Collector-Base Breakdown Voltage	VCBO	50	V
Collector-Emitter Breakdown Voltage	VCEO	45	V
Emitter-Base Breakdown Voltage	VEBO	5	V
Collector Current	IC	500	mA
Collector Power Dissipation	Pc	300	mW
Junction Temperature	TJ	-65~150	°C
Storage Temperature	Tstg	-65~150	°C

Electrical Characteristics (Ta 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Max	Unit
Collector-Base Breakdown Voltage	VCBO	IC=100uA IE=0	50		V
Collector-Emitter Breakdown Voltage	VCEO	IC=1mA IB=0	45		V
Emitter-Base Breakdown Voltage	VEBO	IE=100uA IC=0	5		V
Collector Cutoff Current	ICBO	VCB=50V IE=0		100	nA
Collector Cutoff Current	ICEO	VCE=45V IB=0		100	nA
Emitter Cutoff Current	IEBO	VEB=5V IB=0		100	nA
DC Current Gain	HFE(A)	VCE=1V IC=100mA	100	600	
	HFE(B)	VCE=1V IC=500mA	40		
Collector-Emitter Saturation Voltage	VCE(sat)	IC=500mA IB=50mA		0.7	V
Collector-Base Saturation Voltage	VBE(sat)	IC=500mA IB=50mA		1.2	V
Base-Emitter Voltage	VBE(on)	IC=500mA VCE=1V		1.2	V
transition frequency	fT	VCE=5V IC=10mA f=100MHz	100		MHz

REEL TAPING SPECIFICATIONS FOR SURFACE MOUNT DEVICES-SOT-23

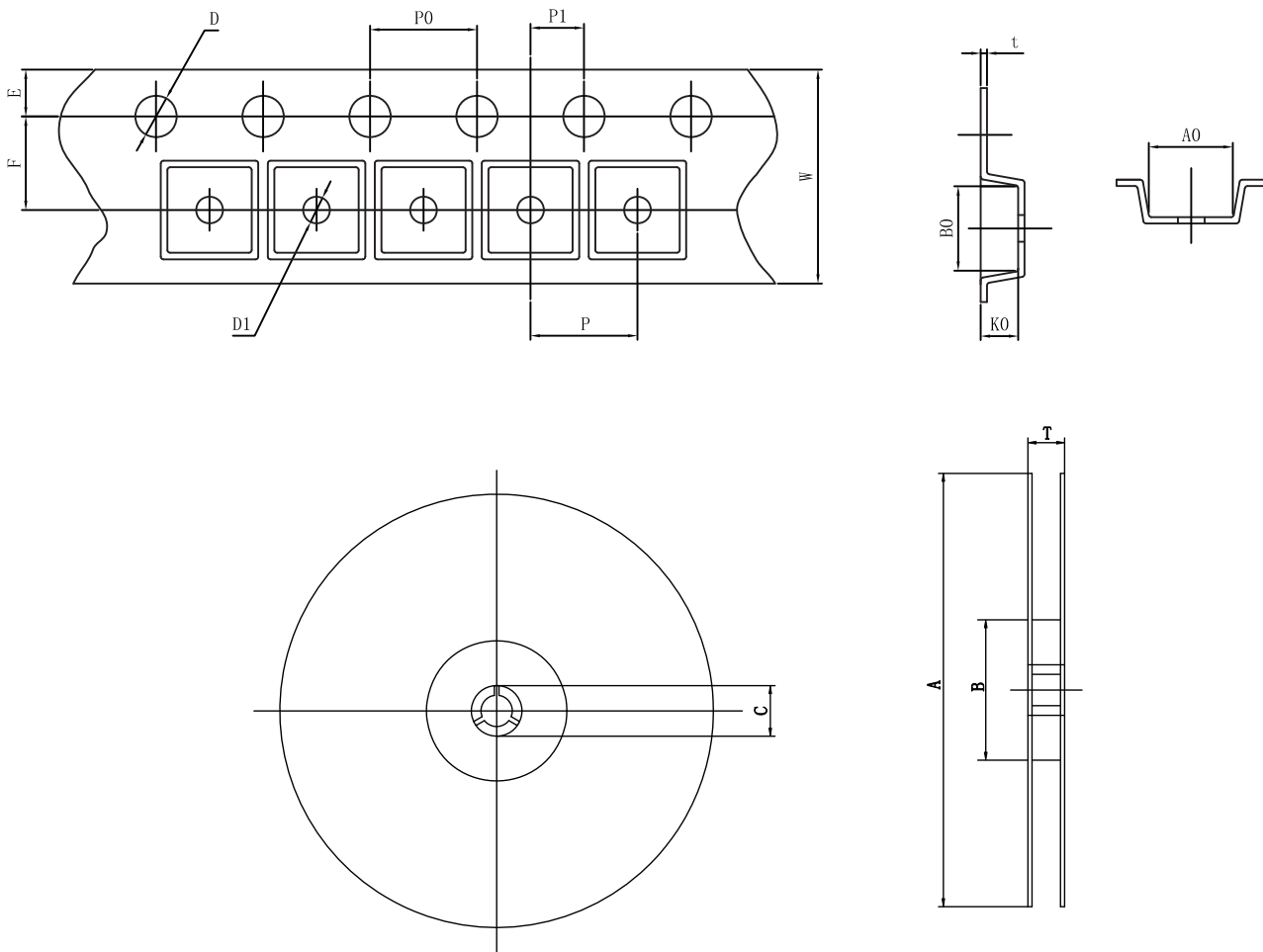


Fig.: Configuration of SOT-23 TAPING

ITEM	SYMBOL	SPECIFICATIONS (mm)	SPECIFICATIONS (inch)
Carrier width	A0	3.25 Max.	0.128 Max.
Carrier length	B0	2.87 Max.	0.113 Max.
Carrier depth	K0	1.32 Max.	0.052 Max.
Sprocket hole	D	1.5+0.1/0	0.059+0.004/0
Reel outside diameter	A	178±1.0	7.009±0.039
Reel inner diameter	B	54 Min.	2.126 Min.
Feed hole diameter	C	13.0±0.20	0.512±0.008
Sprocket hole position	E	1.75±0.10	0.069±0.004
Punch hole position	F	3.5±0.05	0.138±0.002
Punch hole pitch	P	4.0±0.10	0.158±0.004
Sprocket hole pitch	P0	4.0±0.10	0.158±0.004
Embossment center	P1	2.0±0.05	0.079±0.002
Overall tape thickness	t	0.242 Max.	0.010 Max.
Tape width	W	8.0+0.3/-0.1	0.315+0.012/-0.004
Reel width	T	12.5 Max.	0.492 Max.
Punch hole diameter	D1	1.05 Max.	0.041 Max.

Note : Devices are packed in accordance with EIA standard RS-481-A and specification given above. Available only for SOT-23 devices.

PACKAGING OF DIODE

REEL PACK

PACKAGE	PACKING CODE	REEL (EA)	COMPONENT SPACE(mm)	TAPE SPACE (mm)	REEL DIA (mm)	CARTON SIZE (mm)	EA PER CARTON	GROSS WEIGHT(Kg)
SOT-23/-3L	-T	3,000	---	---	178	438*438*220	180,000	---

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